

REMARKS

Rejection of Claims 7-8 and 17

Claims 7-8 and 17 stand rejected under 35 USC § 102(b) as anticipated by Nobushi et al. The Examiner's rejection on this ground is respectfully traversed.

Claim 7 has been amended to more broadly require that the elongated leads be formed on the surfaces of the substrate and the sacrificial layer rather than specifying that they have deposited thereon.

Claim 7 has also been amended to specify that the sacrificial layer is removed by etching. Such etching process is neither disclosed nor suggested in Nobushi et al. To the contrary, Nobushi discloses that the "sacrificial layer" 2B should be made of a separate piece of wood which can be peeled from the leads 8' rather than etched therefrom. This is an undesirable and unacceptable process since, *inter alia*, it significantly increases the likelihood that the leads would be injured during the removal process. Accordingly, claim 7 is believed to be in condition for allowance.

Claim 8 depends from claim 7 and it includes all of the limitations found therein. Claim 8 further requires that the sacrificial layer be formed "in said substrate before said depositing step." This is clearly not shown or suggested in Nobushi et al. Nobushi et al. teaches that the sacrificial layer is a separate, adjacent layer and is not formed in the substrate. Accordingly, claim 8 is believed to be in condition for allowance.

Claim 17 has been amended to specify that "the sacrificial layer [is] made of a material which is different than the material of the substrate". In contrast, Nobushi et al. teaches that both the substrate and the "sacrificial layer" should be made of the same material. Accordingly, claim 17 is believed to be directed towards patentable subject matter. Claim 17 reads on all three disclosed embodiments of the application.

Rejection of Claims 1-2

Claims 1-2 stand rejected 35 USC § 103 as unpatentable over Shimada et al. in view of Nobushi et al. The Examiner's rejection on this ground is respectfully traverse.

The Examiner has relied on two separate embodiments of Shimada et al. in his rejection. The first embodiment is shown in Figures 1-5. The second embodiment is shown in Figures 6-7. Each embodiment will be discussed separately.

In the first embodiment, a sacrificial layer 23 is formed in the substrate 1. However, this embodiment does not form a number of leads on the surface of the substrate 1, nor does it form a cut extending from the bottom surface of the substrate 1 into the sacrificial layer 23 as required by claim 1. Accordingly, the first embodiment neither discloses nor suggests the invention of claim 1.

In the second embodiment, a sacrificial layer 35 (Figure 6B) is formed in a recess of the plating substrate 31. However, this embodiment does not form a number of leads on the surface of the substrate which leads extend into an area of the sacrificial layer, nor does this embodiment form a cut extending from the bottom surface of the substrate 37 into the sacrificial layer as required by claim 1. Accordingly, this embodiment of Shimada et al. neither discloses nor suggests the invention of claim 1.

Claim 2 depends from claim 1 and includes all of the limitations found therein and is also believed to be in condition for allowance.

Miscellaneous Matter

As shown in the stamped postcard attached hereto (**Exhibit A**), applicants have both filed a claim for priority and submitted the priority documents in the present case. It is requested that the Examiner acknowledge the claim for priority and the filing of the priority document.

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In view of the foregoing, it is believed that the application is now in condition for allowance. Reconsideration and allowance of the application are earnestly solicited.

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Respectfully submitted,

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Attachment